# Fabrication of As-doped n-type BaSi<sub>2</sub> epitaxial films grown by molecular beam epitaxy

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We grow As-doped BaSi<sub>2</sub> epitaxial films by molecular beam epitaxy (MBE) with GaAs granules as an As source and investigated their electrical and optical properties by changing a substrate temperature ( $T_s$ ) and a crucible temperature of GaAs ( $T_{GaAs}$ ) during MBE. Secondary ion mass spectrometry revealed that the density of As atoms in BaSi<sub>2</sub> films was surely changed by  $T_{GaAs}$ . The full width at half-maximum evaluated by the x-ray  $\omega$ -scan rocking curve measurement reached a minimum of 0.36 ° at  $T_s = 600$  °C. We investigated the  $T_s$  dependence of electron concentration (n) and mobility by Hall measurement. n increased with decreasing  $T_s$  and reached a maximum of  $4.3 \times 10^{18}$  cm<sup>-3</sup>. The photoresponsivity of the As-doped BaSi<sub>2</sub> films was higher than that of undoped ones at the same bias voltage, probably thanks to the reduction of point defects by As doping.

### 1. Introduction

Barium silicide (BaSi<sub>2</sub>) has been attracting considerable attention as a new candidate for thin film solar cell materials.<sup>1)</sup> BaSi<sub>2</sub> consists of Si and Ba, which are abundant elements in the earth's crust, and the band gap of BaSi<sub>2</sub> (1.3 eV) is suitable for solar cell applications.<sup>2-4)</sup> Moreover, a large absorption coefficient (3  $\times$  10<sup>4</sup> cm<sup>-1</sup> at 1.5 eV) exceeding those of Cu(In,Ga)(Se,S)<sub>2</sub> is compatible with an ample minority carrier lifetime (> 10 µs).<sup>5,6)</sup> Very recently, we achieved the conversion efficiency of 9.9% in p<sup>+</sup>-BaSi<sub>2</sub>/n-Si heterojunction solar cells.<sup>7-9)</sup> In addition, the operation of a BaSi<sub>2</sub> homojunction solar cell was demonstrated on a p-Si(111) substrate.<sup>10,11</sup> In this structure, an antimony (Sb)-doped n-BaSi<sub>2</sub> layer<sup>12</sup> was used for the topmost layer. This is because a low-temperature-grown Sb-doped n-BaSi<sub>2</sub> layer is suitable only to the topmost layer since the diffusion coefficient of Sb in BaSi<sub>2</sub> is very large.<sup>13)</sup> However, the following problem arises when the layered structure is n-BaSi2/p-BaSi2/p-Si. Due to a small electron affinity of BaSi<sub>2</sub> (0.32 eV),<sup>14</sup> there is a large conduction band offset of approximately 0.8 eV and a large valence band offset of approximately 0.6 eV at BaSi<sub>2</sub>/Si heterointerfaces when a Si substrate is adopted.<sup>15)</sup> Therefore, the flow of photogenerated carriers is blocked by these band offsets at the p-BaSi<sub>2</sub>/p-Si interface as shown in Fig. 1(a). It is therefore necessary to form a  $p^+$ -BaSi<sub>2</sub>/ $p^+$ -Si tunnel junction when a p-type Si substrate is used. However, the crystallinity of p<sup>+</sup>-BaSi<sub>2</sub> films grown on a low-resistivity ( $\rho$ ) p<sup>+</sup>-Si substrate degrades,<sup>16</sup> leading to the decrease of shunt resistance and thereby much smaller efficiencies than expected.<sup>17)</sup> In this study, we propose an alternative structure, that is a BaSi<sub>2</sub> homojunction solar cell on an n-Si substrate as shown in Fig. 1(b). In this structure, a tunnel junction is not necessary since the flow of photogenerated carriers is not blocked at the n-BaSi2/n-Si heterointerface. To realize this structure, it is indispensable to explore n-BaSi<sub>2</sub> films doped with impurities other than Sb.

The valence band maximum of BaSi<sub>2</sub> is composed mainly of Si 3s and 3p orbitals and it is reported that Si atoms are more easily substituted than Ba atoms in the lattice.<sup>2,18)</sup> Therefore, substitution of Si atoms with group 15 elements such as Sb, arsenic (As), and phosphorous (P) increases the valence electron concentration,<sup>11,19,20)</sup> and therefore n-type BaSi<sub>2</sub> forms. Regarding As-doped BaSi<sub>2</sub> and P-doped BaSi<sub>2</sub>, the n-type conductivity was reported by ion implantation;<sup>19,20)</sup> however, the electron concentration *n* does not exceed 10<sup>18</sup> cm<sup>-3</sup> in P-doped BaSi<sub>2</sub> films by molecular beam epitaxy (MBE).<sup>21)</sup> On the other hand, there has been no report thus far on As-doped n-BaSi<sub>2</sub> grown by MBE. We should also note that the diffusion coefficient of As atoms in BaSi<sub>2</sub> films is much smaller than those of Sb.<sup>12)</sup> In this work, we thereby aim to fabricate As-doped n-BaSi<sub>2</sub> epitaxial films grown by MBE and evaluate their electrical and optical properties. We employed GaAs granules as a source of As rather than elemental As. As atoms are supplied in the form of As<sub>2</sub> from GaAs granules, whereas As<sub>4</sub> molecules are supplied from elemental As sources.<sup>22)</sup> According to ref. 23, As<sub>2</sub> is more easily decomposed into As atoms than As<sub>4</sub>, enabling us to substitute some of Si atoms with As atoms in the BaSi<sub>2</sub> lattice more efficiently. We can neglect the doping effect of Ga atoms. This is because the vapor pressure of Ga is much smaller than that of As<sub>2</sub>.<sup>23)</sup>

#### 2. Experiment method

As-doped Si and BaSi<sub>2</sub> epitaxial films were formed on p-Si(111) substrates by MBE equipped with an electron-beam gun for Si and Knudsen cells for Ba and GaAs. For Hall measurement, high-resistivity ( $\rho > 1000 \ \Omega$ cm) p-Si(111) substrates were used. In contrast, low- $\rho$  (< 0.01  $\Omega$ cm) n<sup>+</sup>-Si(111) substrates were used for photoresponsivity measurement. The fabrication procedure of As-doped Si films is as follows. After thermal cleaning (TC) of the Si substrate by heating at 900 °C for 30 min in ultrahigh vacuum, As-doped Si films were grown at a fixed substrate temperature  $T_{\rm S} = 600$  °C by MBE. The thickness of As-doped Si films was approximately 150 nm. The crucible temperature of GaAs was set at  $T_{\rm GaAs} = 550$ , 650, and 750 °C. Finally, a 3-nmthick amorphous Si (a-Si) capping layer was formed *in situ* at  $T_{\rm S} = 180$  °C. 1-mm-diameter A1 electrodes with a thickness of 150 nm were deposited by sputtering.

We next grew As-doped BaSi<sub>2</sub> epitaxial films as follows. After TC, a few-nm-thick BaSi<sub>2</sub> template layer was formed by reactive deposition epitaxy, in which only Ba was supplied on a heated Si substrate. This layer works as a seed crystal for overlayers.<sup>24)</sup> After that, As-doped BaSi<sub>2</sub> films were formed by MBE at various values of  $T_{GaAs}$  and  $T_{s.}^{25, 26)}$  First,  $T_{GaAs}$  was varied in the range 250 – 450 °C while  $T_{s}$  was fixed at 600 °C. As described later, however, we were not able to control *n* by changing  $T_{GaAs}$ . Therefore, we next set  $T_{GaAs}$  at 350 °C and varied  $T_{s}$  in the range 500 – 700 °C. For photoresponsivity measurement,  $T_{GaAs}$  was changed from 250 to 450 °C with keeping  $T_{s}$  constant at 600 °C. The thickness of As-doped BaSi<sub>2</sub> films was approximately 500 nm. Then, a 3-nm-thick a-Si capping layer was formed for surface passivation.<sup>27)</sup> The bond configuration changes abruptly at the BaSi<sub>2</sub> surface. According to an analysis of the surface structure of BaSi<sub>2</sub> epitaxial layers using coaxial-collision ion scattering

spectroscopy conducted by Katayama *et al.*, an *a*-axis-oriented BaSi<sub>2</sub> epitaxial films is terminated by Si<sub>4</sub> tetrahedra.<sup>28,29)</sup> Therefore, surfaces may contain very high densities of trap states in the band gap.<sup>30)</sup> Such surface defects deteriorate solar cell performance because short-wavelength light is absorbed close to the surface. Therefore, surface passivation is very important for materials like BaSi<sub>2</sub> that possess large absorption coefficients. Finally, 1-mm-diameter ITO electrodes with the thickness of 80 nm on the surface and Al electrodes with the thickness of 150 nm on the whole back side were formed by sputtering.

Crystalline quality of grown films was characterized by  $\theta$ -2 $\theta$  X-ray diffraction (XRD; Rigaku Smart Lab) using Cu K $\alpha$  radiation, and reflection high-energy electron diffraction (RHEED). Depth profiles of As atoms were evaluated by secondary ion mass spectrometry (SIMS) with Cs<sup>+</sup> ions. Hall measurement was performed with Van der Pauw method.<sup>31)</sup> Photoresponse spectra were collected at a bias voltage ( $V_{\text{bias}}$ ) of -0.5 V applied to the front ITO electrode with respect to the backside Al electrode by a lock-in technique using a xenon lamp (Bunko Keiki, SM-1700A) and a single monochromator with a focal length of 25 cm (Bunko Keiki, RU-60N). The light intensity of the lamp was calibrated using a pyroelectric sensor (Melles Griot, 13PEM001/J). All the measurement was performed at room temperature.

#### 3. Results and discussion

Figure 2 shows the  $T_{\text{GaAs}}$  dependences of *n* and mobility  $\mu$  of As-doped Si films.  $T_{\text{S}}$  was fixed at 600 °C. Hall measurement revealed that *n* increased with  $T_{\text{GaAs}}$ , and *n* reached a maximum of 3.7 × 10<sup>18</sup> cm<sup>-3</sup> at  $T_{\text{GaAs}} = 750$  °C. The  $\mu$  decreased accordingly. This result was in agreement with those reported on As-doped n-Si films by using GaAs as a source of As.<sup>32</sup>

After confirming the formation of n-Si films by heating GaAs granules, we next move on to As-doped BaSi<sub>2</sub> films. First, we checked the presence of As atoms in the grown films by SIMS. Figure 3(a) and 3(b) show the depth profiles of As atoms in As-doped BaSi<sub>2</sub> films and secondary ion intensity of Ba + Si in As-doped BaSi<sub>2</sub> films grown at  $T_{GaAs} = 350$  and 750 °C, respectively.  $T_S$  was set at 600 and 650 °C, respectively. Please note that the measured As concentration ( $N_{As}$ ) was not corrected because reference samples with a controlled number of As atoms doped in BaSi<sub>2</sub> films have not yet been prepared. In this work, we employed As-doped Si as a reference.  $N_{As}$  was approximately  $3 \times 10^{18}$  cm<sup>-3</sup> in Fig. 3(a) and approximately  $10^{22}$  cm<sup>-3</sup> in Fig. 3(b). The limit of detection by SIMS is approximately  $4 \times 10^{17}$  cm<sup>-3</sup>. There results mean that the *N*<sub>As</sub> changes by *T*<sub>GaAs</sub> in BaSi<sub>2</sub> films.

Figure 4(a) shows the  $\theta$ -2 $\theta$  XRD patterns and RHEED patterns observed along the Si[11-2] azimuth after the growth of As-doped BaSi<sub>2</sub> films. *T*s was varied in the range 500 – 700 °C, while *T*<sub>GaAs</sub> was fixed at 350 °C. In all the samples, the diffraction peaks corresponding to *a*-axisoriented BaSi<sub>2</sub> films were detected. Therefore, *a*-axis-oriented As-doped BaSi<sub>2</sub> films was grown regardless of *T*s. In the sample grown at *T*s = 500 °C, however, streaky RHEED pattern was not obtained. In contrast, for samples grown at 550 °C  $\leq$  *T*s  $\leq$  700 °C, streaky RHEED patterns were observed. On the basis of these results, we can state that *a*-axis-oriented As-doped BaSi<sub>2</sub> films were grown epitaxially in the range of *T*s = 550 – 700 °C. To find the optimum *T*s among them, we evaluated the *T*s dependence of the full width at half-maximum (FWHM) of BaSi<sub>2</sub> 600 peak by  $\omega$ -scan x-ray rocking curve measurement. The result is presented in Fig. 4(b). The FWHM decreased with *T*s, reached a minimum of 0.36 ° at *T*s = 600 °C, and increased for higher *T*s, suggesting that the optimum *T*s was 600 °C from the viewpoint of crystalline quality. Similar tendency of FWHM values against *T*s was reported for undoped BaSi<sub>2</sub> films.<sup>33)</sup>

We therefore set *T*s at 600 °C and changed  $T_{GaAs}$  from 250 to 450 °C to form As-doped n-BaSi<sub>2</sub> films. In contrast to our prediction, however, we could not control *n* by changing  $T_{GaAs}$  at  $T_S = 600$  °C. Figure 3(a) shows the presence of As atoms in the BaSi<sub>2</sub> films grown at  $T_S = 600$  °C and  $T_{GaAs} = 350$  °C. The increase of  $T_{GaAs}$  increases the concentration of As atoms in the BaSi<sub>2</sub> films. Therefore, the fact that the *n* of As-doped BaSi<sub>2</sub> films cannot be controlled by  $T_{GaAs}$  means that doped As atoms did not occupy the Si sites in the lattice of BaSi<sub>2</sub>. Similar results were obtained in Sb-doped BaSi<sub>2</sub> films in ref. 12. Thereby, we next fixed  $T_{GaAs}$  at 350 °C and varied  $T_S$  from 500 to 700 °C for As-doped BaSi<sub>2</sub> films. Figure 5 shows the  $T_S$  dependence of *n* and  $\mu$  of As-doped BaSi<sub>2</sub> films. *n* increased with decreasing  $T_S$ , and reached  $4.3 \times 10^{18}$  cm<sup>-3</sup> at  $T_S =$ 550 °C. This value of *n* is acceptable for the bottom layer of a BaSi<sub>2</sub> homojunction solar cell. *n* decreased sharply when  $T_S$  was 600 °C and over. This result shows that the value of *n* can be controlled by  $T_S$ . The value of  $\mu$  decreased with increasing  $T_S$ . As shown in Fig. 4(b), the crystalline quality of BaSi<sub>2</sub> films degraded for samples grown at  $T_S > 600$  °C. We therefore attribute such reduction of  $\mu$  partly to the degradation of crystalline quality of As-doped BaSi<sub>2</sub> films.

Figure 6 shows the photoresponse spectra of As-doped BaSi<sub>2</sub> films grown with  $T_{GaAs}$  = 250 – 450 °C. T<sub>s</sub> was fixed at 600 °C. A V<sub>bias</sub> of -0.5 V was applied to the front ITO electrode with respect to the backside Al electrode. Photoresponsivity was increased with  $T_{GaAs}$ , and reached a maximum of approximately 0.8 A/W at a wavelength of 800 nm for sample grown at  $T_{\text{GaAs}} = 350$  °C. The obtained photoresponsivity was higher than that of undoped BaSi<sub>2</sub> films at the same value of  $V_{\text{bias}}$ .<sup>34)</sup> We attribute this improvement of photoresponsivity to the reduction of point defects in As-doped BaSi2 films. In undoped BaSi2 films, photoresponsivity and carrier lifetime were improved significantly by hydrogen (H) passivation.<sup>35)</sup> H atoms in BaSi<sub>2</sub> films are considered to inactivate Si vacancies, which are most likely to form in BaSi2.36) Likewise, we speculate that inactivation of Si vacancies by doping As atoms in As-doped BaSi<sub>2</sub> films occurs. The photoresponsivity is proportional of the ratio of carrier lifetime to carrier transit time,<sup>37)</sup> meaning that the reduction of carrier mobility decreases the photoresponsivity. As shown in Fig. 5, the electron mobility of As-doped BaSi<sub>2</sub> films decreases with  $T_{\rm S}$ . This is caused by the degradation of crystalline quality of As-doped BaSi<sub>2</sub> films as shown in Fig. 4(b), suggesting that the mobility of photogenerated holes also decreases with  $T_{\rm S}$ . Therefore, we consider the reason why the photoresponsivity reaches a maximum at a certain value ( $T_{GaAs} = 350$  °C) as follows. The photoresponsivity increases with  $T_{GaAs}$  because of the reduction of point defects by doped As atoms. However, further increase of As atoms degrades the crystalline quality of As-doped BaSi2 films, leading to the reduction of carrier mobilities and therefore photoresponsivity.

#### 4. Conclusion

We fabricated As-doped n-BaSi<sub>2</sub> films grown by MBE and evaluated their electrical and optical properties. Highly *a*-axis-oriented As-doped BaSi<sub>2</sub> films were grown epitaxially on Si(111) substrates. The optimum  $T_S$  of As-doped BaSi<sub>2</sub> was 600 °C in terms of crystalline quality. *n* increased with decreasing  $T_S$ , and reached a maximum of  $4.3 \times 10^{18}$  cm<sup>-3</sup> at  $T_S = 550$  °C and  $T_{GaAs} = 350$  °C. Moreover, photoresponsivity was enhanced by As doping and the highest photoresponsivity was obtained for As-doped BaSi<sub>2</sub> films at  $T_S = 600$  °C and  $T_{GaAs} = 350$  °C. We ascribe the higher photoresponsivity of As-doped BaSi<sub>2</sub> films compared to undoped BaSi<sub>2</sub> films to the reduction of point defects by As doping as is the case with atomic hydrogen passivated BaSi<sub>2</sub> films.

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## **Captions of figures**

Fig. 1. Schematic of band alignments and the flow of photogenerated carriers in (a) n-BaSi<sub>2</sub>/p-BaSi<sub>2</sub> on p-Si and (b) p-BaSi<sub>2</sub>/n-BaSi<sub>2</sub> on n-Si under illumination.

Fig. 2.  $T_{\text{GaAs}}$  dependence of *n* and  $\mu$  of As-doped Si grown with  $T_{\text{GaAs}} = 550 - 750$  °C. *T*s is 600 °C.

Fig. 3. SIMS depth profile of  $N_{As}$  and secondary ions (Ba + Si) of BaSi<sub>2</sub> films grown with (a)  $T_{GaAs} = 350 \text{ °C}$ , (b)  $T_{GaAs} = 750 \text{ °C}$ .  $T_S$  is 600 °C in (a) and 650 °C in (b).

Fig. 4. (a)  $\theta$ -2 $\theta$  XRD and RHEED patterns of As-doped BaSi<sub>2</sub> films taken along the Si [11-2] azimuth for samples grown at  $T_{\rm S} = 500 - 700$  °C.  $T_{\rm GaAs}$  is 350 °C, and (b)  $T_{\rm S}$  dependence of FWHM values of BaSi<sub>2</sub> 600 peaks for samples grown at  $T_{\rm S} = 500 - 700$  °C, evaluated by x-ray  $\omega$ -scan rocking curve measurement.

Fig. 5.  $T_S$  dependences of *n* and  $\mu$  of As-doped BaSi<sub>2</sub> films grown with  $T_S$  of 500 – 700 °C.  $T_{GaAs}$  is 350 °C.

Fig. 6. Photoresponse spectra of As-doped BaSi<sub>2</sub> films grown with  $T_{GaAs} = 250 - 450$  °C and  $T_S = 600$  °C at  $V_{bias} = -0.5$  V.

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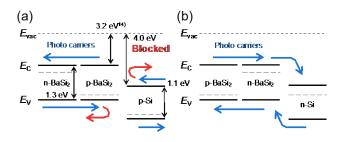


Fig. 1

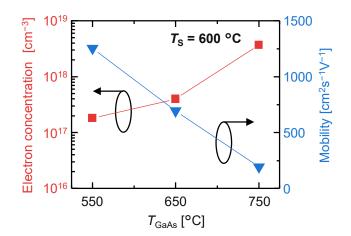


Fig. 2

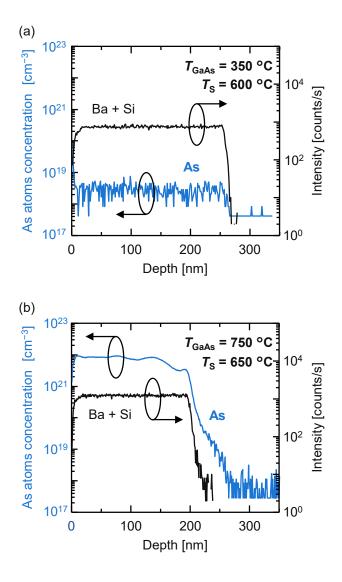


Fig. 3

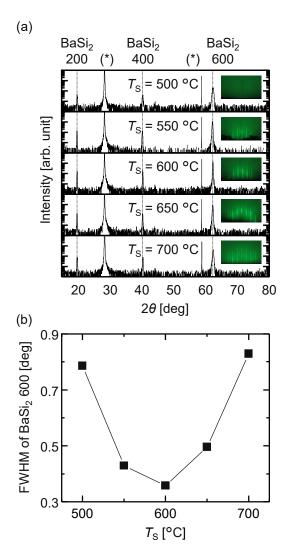


Fig. 4

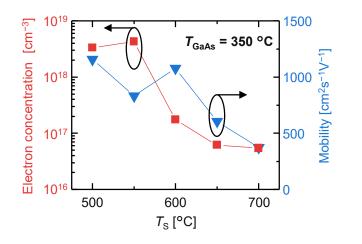


Fig.5

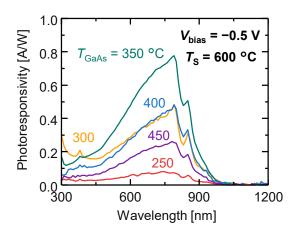


Fig. 6